Overview

HP ProBook 430 G6 Notebook PC



Left

- 1. Internal microphones (2)
- 2. Webcam
- 3. Webcam LED
- 4. Clickpad
- 5. Hard drive LED

- 6. SD Card reader
- 7. Thermal vent
- 8. USB 3.1 Gen 1 port
- 9. Security lock slot (Lock sold separately)
- 10. Power button



Overview



Right

- 1. Power connector
- 2. USB Type-C[™] 3.1 Gen 1 port
- 3. Ethernet port (RJ-45)
- 4. HDMI port (Cable not included)

- 5. USB 3.1 Gen 1 port
- 6. Headphone/microphone combo jack
- 7. HP Fingerprint Sensor



Overview

At a Glance

- Preinstalled with Windows 10 versions or FreeDOS 3.0
- Choice of 8th Generation Intel[®] Core[™] i7, i5, i3 processors
- Display include your choice of 33.8 cm (13.3") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen
- Integrated Intel[®] HD Graphics 610 and intel[®] UHD 620
- Enhanced security features including TPM2.0, HP BIOSphere, Hardware enforced Firmware Protection, optional Fingerprint sensor, and optional IR camera
- Passed 19 items of MIL-STD 810G testing plus an additional 120,000 hours of reliability testing through HP's Total Test Process¹
- Weight starting at 3.28 lbs (1.49 kgs)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Supports wireless LAN and wireless WWAN options for connectivity on the go
- Up to 512 GB Solid State Drives or 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard with numeric keypad, and Clickpad with multi-touch gestures enabled, taps enabled as default
- Enjoy the rich conferencing experience of the Skype for Business™ Certified HP ProBook 430
 - 1. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.
 - 2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAMES

HP ProBook 430 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64¹ Windows 10 Pro 64 (National Academic only)² Windows 10 Home 64¹ Windows 10 Home Single Language 64¹ Windows 10 China Government Edition FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel[®] Core[™] i7-8565U with Intel[®] UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-8265U with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i3-8145U with Intel[®] UHD Graphics 620 (2.1 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel[®] Core[™] i7+ 8565U processor (Core[™] i7 and 16 GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel[®] Core[™] i5+ 8265U processor (Core[™] i5 and 16 GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel[®] Celeron[®] 4205U processor with Intel[®] HD Graphics 610 (1.8 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6} Intel[®] Pentium[®] 5405U processor with Intel[®] HD Graphics 610 (2.3 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6}

Processors Family

8th Generation Intel[®] Core[™] i7 processor (i7-8565U)⁶ 8th Generation Intel[®] Core[™] i5 processor (i5-8265U)⁶ 8th Generation Intel[®] Core[™] i3 processor (i3-8145U)⁶ Intel[®] Pentium[®] processor (5405U)⁶ Intel[®] Celeron[®] processor (4205U)⁶

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.



 NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

7. Intel[®] Optane[™] memory system acceleration does not replace or increase the DRAM in your system and requires configuration with an optional Intel[®] Core[™] i(5 or 7)+ processor.

CHIPSET

Integrated with processor

GRAPHICS

Integrated Intel[®] UHD graphics 620⁸

8. HD content required to view HD images.

DISPLAYS

Internal

Non-Touch

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m², 67% sRGB for two WLAN antennas (1366 x 768)^{8,10}

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1366 x 768)^{8,10}

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m², 67% sRGB for HD+IR camera and two WLAN antennas (1366 x 768)^{8,10}

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768)^{8,10}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1920 x 1080)^{8,10}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD+IR camera and two WLAN antennas (1920 x 1080)^{8,10}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080)^{8,10}

Touch

33.8 cm (13.3") diagonal HD SVA eDP LED-backlit Ultraslim touch screen, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1366 x 768)^{8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP LED-backlit slim touch screen, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1920 x 1080)^{8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP LED-backlit slim touch screen, 220 cd/m², 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080)^{8,9,10}

HDMI

Supports resolutions up to 4K 30Hz

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.



Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt- mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary Storage

500 GB 7200 rpm SATA¹¹ 1 TB 5400 rpm SATA¹¹

Primary M.2 Storage

128 GB M.2 SATA TLC Solid State Drive¹¹ 256 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹¹ 512 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹ 512 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹¹

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

NOTE: PCIe SSD not available for Celeron

MEMORY

Memory

32 GB DDR4-2400 SDRAM (2 x 16 GB)¹² 16 GB DDR4-2400 SDRAM (1 x 16 GB) 16 GB DDR4-2400 SDRAM (2 x 8 GB)¹² 12 GB DDR4-2400 SDRAM (4 GB and 8 GB (1 x 8 GB)¹² 8 GB DDR4-2400 SDRAM (1 x 8 GB) 8 GB DDR4-2400 SDRAM (2 x 4 GB)¹²



4 GB DDR4-2400 SDRAM (1 x 4 GB)

Maximum 32 GB DDR4-2400 SDRAM¹²

Memory Slots 2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Wireless LAN (WLAN)

Realtek 802.11ac (2x2) WLAN and Bluetooth[®] 4.2 Combo¹³ Intel[®] Dual Band Wireless-AC 9560 802.11ac (2x2) WLAN and Bluetooth[®] 5.0 Combo, non-vPro^{™13}

Broadband Wireless (WWAN)

Intel[®] XMM[™] 7262 LTE-Advanced (Cat6)¹⁴ Intel[®] XMM[™] 7360 LTE-Advanced (Cat9)¹⁴

Ethernet

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC¹⁵

- 13. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- 14. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Integrated microphone (Mono or Dual Array) 2 Integrated stereo speakers

Speaker Power 2W/40hm Per speaker

Camera 720p HD camera⁸ 720p HD camera+IR Camera^{8,9}

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - numlk F11 - Wireless F12 – Sleep **Hidden Functions** Fn+R - Break

Fn+S - Sys Rg Fn+C - Scroll Lock Fn+E - Insert

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen4¹⁶ HP DriveLock & Automatic DriveLock **BIOS Update via Network** Secure Erase¹⁷ Absolute Persistence Module¹⁸ **Pre-boot Authentication** HP Wireless Wakeup

Software

HP Native Miracast Support¹⁹ **HP LAN-Wireless Protection HP** Connection Optimizer HP 3D DriveGuard HP Hotkey Support - CMIT **HP** Jumpstart HP Support Assistant²⁰ **HP Noise Cancellation Software**



Technical Specifications

HP Host Based MAC Address Manager Buy Office (sold separately)

Manageability Features

HP Driver Packs²¹ HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen2²² Ivanti Management Suite²³ HP Cloud Recovery²⁴

Client Security Software

HP Client Security Suite Gen4²⁵ including: HP Security Manager²⁶ (including Credential Manager, HP Password Manager, HP Spare Key) HP Fingerprint Sensor²⁷ HP Device Access Manager²⁸ HP Power On Authentication Windows Defender²⁹

Security Management

Secure Erase¹⁷ TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³⁰ SATA 0,1 port disablement (viaBIOS) RAID configurations³¹ Serial, USB enable/disable (viaBIOS) Power-on password (viaBIOS) Setup password (viaBIOS) Support for chassis padlocks and cable lock devices Integrated hood sensor HP Sure Click³²

- 16. HP BIOSphere Gen4 requires Intel(R) or AMD 8th Gen processors. Features may vary depending on the platform and configurations.
- 17. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 18. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.



- 19. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 20. HP Support Assistant requires Windows and Internet access.
- 21. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 22. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 23. Ivanti Management Suite subscription required
- 24. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 25. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
- 26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 27. HP Fingerprint Sensor sold separately or as an optional feature.
- 28. HP Device Access Manager requires HP Client Security Suite Gen4.
- 29. Windows Defender Opt in and internet connection required for updates.
- 30. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 31. RAID configuration is optional and does require a second hard drive.
- 32. HP Sure Click is available on most HP PCs and supports Microsoft[®] Internet Explorer and Chromium[™]. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

POWER

HP Smart 65 W External AC power adapter³³ HP Smart 65 W EM External AC power adapter³³ HP Smart 65 W USB Type-C[™] adapter³³ HP Smart 45 W External AC power adapter³³ HP Smart 45 W USB Type-C[™] adapter³³

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion³⁴

Power Cord

3-wire plug - 1m³³ 3-wire plug - 1.8m³³ 2-wire plug - 1m³³ Duckhead power cord- 1m³³ Duckhead power cord- 1.8m³³

Battery Life

Up to 14 hours ³⁵

Battery Weight 0.49 lb 0.22 kg

33. Availability may vary by country.

34. Battery is internal and not replaceable by customer. Serviceable by warranty.



35. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 3.28 lb³⁶ Starting at 1.49 kg³⁶

Dimensions (w x d x h)

12.15 x 9.09 x 0.71 in 30.85 x 23.1 x 1.8 cm

36. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C[™] Gen 1 (Power delivery, DisplayPort[™])
1 USB 3.1 Gen 1
1 USB 3.1 (Powered port)
1 HDMI 1.4b³⁷
1 RJ-45
1 AC power
1 Headphone/microphone combo jack

Expansion Slots

1 SD Supports SD, SDHC, SDXC

37. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.³⁸

38. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



ENVIRONMENTAL & INDUSTRY

HP PROBOOK 430 G6 NOTEBOOK PC

Eco-Label Certifications	This product has received or is in t	he process of being certified to	o the following approvals and may	
& declarations	be labeled with one or more of these marks: •IT ECO declaration			
	•US ENERGY STAR®			
		nited States. See http://www.e	epeat.net for registration status in	
	your country.			
	•TCO or TCO Certified Edge			
System Configuration	The configuration used for the Ene	ergy Consumption and Declare	d Noise Emissions data for the	
	Notebook model is based on a Typ	ically Configured Notebook.		
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	5.17 W	5.30 W	5.14 W	
Normal Operation (Long idle)	2.84 W	2.79 W	2.77 W	
Sleep	0.61 W	0.64 W	0.61 W	
Off	0.38 W	0.42 W	0.38 W	
	Energy efficiency data listed is for	an ENERGY STAR® compliant p	product if offered within the model	
	family. HP computers marked with	the ENERGY STAR® Logo are (compliant with the applicable U.S.	
	Environmental Protection Agency			
	family does not offer ENERGY STA			
	for a typically configured PC feature	ring a hard disk drive, a high ei	fficiency power supply, and a	
	Microsoft Windows [®] operating sys	tem.		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	18 BTU/hr	18 BTU/hr	18 BTU/hr	
(Short idle)				
Normal Operation	10 BTU/hr	10 BTU/hr	9 BTU/hr	
(Long idle)				
Sleep	2 BTU/hr	2 BTU/hr	2 BTU/hr	
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr	
	Heat dissipation is calculated base for one hour.	d on the measured watts, ass	uming the service level is attained	
Declared Noise	Sound Power		Sound Pressure	
Emissions	(L _{wAd} , bels)		(L _{pAm} , decibels)	
(in accordance with				
ISO 7779 and ISO 9296)				
Typically Configured – Idle	2.7		24.2	
Fixed Disk – Random writes	2.8 25.1		25.1	
Longevity and Upgrading	This product can be upgraded, pos	sibly extending its useful life I	oy several years. Upgradeable	
	features and/or components contained in the product may include:			
	• 3 USB ports			
	• 1 PC card slot (type I/II)			
	• 1 ExpressCard/54 slot			
	• 1 IEEE 1394 Port			
	 2 SODIMM memory slots 			
	Optional expansion base docking	station		
		Station		
	• 1 multi-bay II storage port			



	Spare parts a production.	re available throughout the warranty period and or for up	to "5" years after the end of		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC				
	Battorios use	d in the product do not contain:			
		ter the1ppm by weight			
		eater than 20ppm by weight			
	Battery size:	CR2032 (coin cell)			
	Battery type	lithium/manganese dioxide			
Additional Information	This produce	t is in compliance with the Restrictions of Hazardous Subs	tances (RoHS) directive -		
	2011/65/EC.	dent in designed to some bestick at a type to Florencia-Land Fl			
	• This HP pro Directive – 20	duct is designed to comply with the Waste Electrical and El	lectronic Equipment (WEEE)		
		t is in compliance with California Proposition 65 (State of C	alifornia: Safe Drinking		
		ixic Enforcement Act of 1986).	allornia, sale brinking		
		t is in compliance with the IEEE 1680.1 (EPEAT) standard a	t the <silver> level in the</silver>		
		://www.epeat.net for registration status by country. Searc			
		y option store for solar generator accessories at http://ww			
		• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.			
		t contains 0% post-consumer recycled plastic (by wt.)			
D		t is 95.1% recycle-able when properly disposed of at end o			
Packaging Materials	External:	PAPER/Corrugated	281 g		
	Internal:	PLASTIC/Polyethylene Expanded - EPE	62 g		
Material Usage		PLASTIC/Polyethylene low density – LDPE	9 g		
	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyl (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.				
	 Nickel – finicarried by the Ozone Depl Polybromin Polybromin Polybromin Polybromin Polychlorin Polychlorin Polyvinyl Cliphing 	shes must not be used on the external surface designed to e user. eting Substances ated Biphenyls (PBBs) ated Biphenyl Ethers (PBBEs) ated Biphenyl Oxides (PBBOs) ated Biphenyl (PCB) ated Terphenyls (PCT) nloride (PVC) – except for wires and cables, and certain reta			
	 Nickel – finicarried by the Ozone Depl Polybromin Polybromin Polybromin Polybromin Polychlorin Polychlorin Polyvinyl Cliphing 	shes must not be used on the external surface designed to e user. eting Substances ated Biphenyls (PBBs) ated Biphenyl Ethers (PBBEs) ated Biphenyl Oxides (PBBOs) ated Biphenyl (PCB) ated Terphenyls (PCT) nloride (PVC) – except for wires and cables, and certain reta emoved from most applications.			



Technical Specifications

De alca ain a llas as	
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	• Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SYSTEM UNIT	
Stand-Alone Power Requirements (AC Power)	
Nominal Operating Voltage	19V
Average Operating Power	Win 10
Integrated graphics	5.71W
Max Operating Power	UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating Shock	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature



Technical Specifications

Operating	40 G, 2 ms, half-sine
Non-operating Random Vibration	200 G, 2 ms, half-sine
Operating	0.75 grms
Non-operating Altitude (unpressurized)	1.50 grms
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating Planned Industry Standard Certifications	-50 to 40,000 ft (-15.24 to 12,192 m)
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR [®]	Selected models ³⁹
EPEAT [®] 2019	Yes, Silver in U.S. ⁴⁰
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
ССС	Yes
Japan VCCI Compliance	Yes
КС	Yes
BSMI	Yes
CE Marking Compliance BNCI or BELUS	Yes
	Yes
CIT	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP) SABS	Yes
UKRSERTCOMPUTER	Yes
	Yes

39. Configurations of the HP ProBook 430 G6 that are ENERGY STAR[®] certified² are identified as HP ProBook 430 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.

40. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch	Outline Dimensions (W x H x D)	300.56 x 187.77 max.
diagonal FHD (1920x1080)	Active Area	293.76 x 165.24 typ.
Anti-Glare WLED UWVA	Weight	<260 max.



•		
45% NTSC 220nits eDP slim	Diagonal Size	13.3"
NB non-touch	Thickness	3.0mm max.
	Interface	eDP 1.2 (2 lanes)
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60Hz
	Brightness	220 nits typical (Panel Only)
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits (Hi FRC @ system GFX output 8bits)
	Viewing Angle	UWVA 85/85/85/85
Panel LCD 13.3 inch	Outline Dimensions (W x H x D)	300.56 x 187.77 max.
diagonal FHD (1920x1080)	Active Area	293.76 x 165.24 typ.
WLED UWVA 45% NTSC	Weight	<383 max.
220nits eDP slim NB touch	Diagonal Size	13.3"
	Thickness	3.2mm max.
	Interface	eDP 1.2 (2 lanes)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60Hz
	Brightness Pixel Resolution	220 nits typical (Panel Only)
		1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	
	Color Gamut Coverage	45% of NTSC 6 bits (Hi FRC @ system GFX output 8bits)
	Color Depth Viewing Angle	0 Dits (m FRC @ System GFX output obits) UWVA 85/85/85/85
	Viewing Angle	000485/85/85/85
Panel LCD 13.3 inch diagonal	Outline Dimensions (W x H x D)	300.56 x 187.77 max. (w/ PCB & w/o bracket)
HD (1366x768) Anti-Glare	Active Area	293.83 x 165.20 typ.
WLED SVA 45% NTSC 220nits eDP slim NB non-touch	Weight	<260 max.
	Diagonal Size	13.3 (inch)
	Thickness	3.0mm max.
	Interface	eDP 1.2 (2 lanes)
	Surface Treatment	Anti-glare
	Touch Enabled	No
	Contrast Ratio	300:1 (typ)



Technical Specifications

	Refresh Rate	60Hz
	Brightness	220 nits typical (Panel Only)
	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits (Hi FRC @ system GFX output 8bits)
	Viewing Angle	SVA 45/45/15/30
		5411 15, 15, 15, 55
Panel LCD 13.3 inch diagonal	Outline Dimensions (W x H x D)	300.56 x 187.77 max. (w/ PCB & w/o bracket)
HD (1366x768) WLED SVA 45% NTSC 220nits eDP	Active Area	293.83 x 165.20 typ.
slim NB touch	Weight	<383 max.
	Diagonal Size	13.3 (inch)
	Thickness	3.2mm max.
	Interface	eDP 1.2 (2 lanes)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	300:1 (typ)
	Refresh Rate	60Hz
	Brightness	220 nits typical (Panel Only)
	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits (Hi FRC @ system GFX output 8bits)
	Viewing Angle	SVA 45/45/15/30

STORAGE AND DRIVES Hard Drives

500 GB 7200 rpm SATA Hard Drive

Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (95 g)
Rotation speed	7200 rpm
Cache Buffer	Up to 32 MB
Height	0.28 in (7 mm)
Width	2.75 in (69.85 mm)
Interface	ATA-8, SATA 3.0
Transfer Rate	600 MB/s
Seek Time	Single Track: 2 ~ 1.5 ms; Average: 11 ~ 13 ms; Maximum: 18 ~ 22 ms
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
Security Features	ATA Security
Features	S.M.A.R.T., NCQ, Ultra DMA



1 TB 5400 rpm SATA	Drive Weight	0.21 lbs (94 g)		
Hard Drive	Rotation speed	5400 rpm		
	Cache Buffer	Up to 32 MB		
	Height	0.28 in (7.2 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 600 MB/s		
	Width			
	Interface			
	Transfer Rate			
	Seek Time	Single Track2 ms		
		Average12 ~ 13 ms Maximum18 ~ 22 ms		
	Logical Blocks			
	Operating Temperature	1,953,525,168 32° to 140° F (0° to 60° C) [top cover temp] ATA Security		
	Security Features			
	Features	S.M.A.R.T., NCQ, Ultra DMA		
SSD 128 GB 2280 M2	Form Factor	M.2 2280		
SSD 128 GB 2280 M2 SATA-3 TLC	Form Factor Capacity	M.2 2280 128GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	ATA-8, SATA 3.0		
	Maximum Sequential Read	Up To 520 MB/s		
	Maximum Sequential Write	Up To 450 MB/s		
	Logical Blocks	250,069,680		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	DIPM; TRIM; DEVSLP		
256 GB 2280 PCIe NVMe	Form Factor	M.2 2280		
Value Solid State Drive	Capacity	256 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	-			
	Width	0.87 in (22 mm)		

Not all configuration components are available in all regions/countries. c06142919 — DA 16310 - Worldwide — Version 13 — July 23, 2019

Up To 1700 MB/s

Up to 1300 MB/s

500,118,192

Maximum Sequential Read

Maximum Sequential Write

Logical Blocks

	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2
512 GB 2280 M2 PCIe NVMe	Form Factor	M.2 2280
TLC Solid State Drive	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up To 2600 MB/s
	Maximum Sequential Write	Up To 1400 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2
16 GB 2280 PCIe-3x2 NVMe		M.2 2280
3D Xpoint Solid State Drive	Capacity	16 GB
	NAND Type	Xpoint
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X2
	Maximum Sequential Read	1400
	Maximum Sequential Write	300
	Logical Blocks	28,181,188
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	L1.2
512 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value Solid State Drive	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up To 1500 ~ 1700 MB/s
	Maximum Sequential Write	Up To 860 ~ 1500MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security, TRIM; L1.2



NETWORKING/COMMUNICATIONS

WWAN

Intel® XMM™ 7262 LTE- Advanced DL CAT6 ¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 (Band 20), 700 (Band 28), HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)		
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to 300Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification		
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)		
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz		
	Maximum data rates	LTE: 300 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)		
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm LTE: 1,200 mA (peak); 830 mA (average) HSPA+: 1,100 mA (peak); 680 mA (average) M.2, 3042-S3 Key B 6 g		
	Maximum power consumption			
	Form Factor			
	Weight			
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm		
	 WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions. 			
Intel® XMM™ 7360 LTE- Advanced CAT9¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band		

vanced CAT9 ¹	bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)



Form Factor	M.2, 3042-S3 Key B	
Weight	5.8 g	
Dimensions (Length x Wid Thickness)	42 30 x 2.3 mm	
purcl	I module is optional, must be configured at the factory and requires separately ased service contract. Check with service provider for coverage and availability in you Connection speeds will vary due to location, environment, network conditions, and o	

factors. 4G LTE not available on all products, in all regions.

WLAN

Intel® 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5.0 Combo ¹ non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi [®] certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz
		802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi[®] compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	Not all configuration of	components are available in all regions/countries.



	• WAPI		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b : +18.5dBm minimum		
	• 802.11g : +17.5dBm minimum		
	• 802.11a : +18.	5dBm minimum	
		2.4GHz) : +15.5dBm minimum	
	-	2.4GHz) : +14.5dBm minimum	
		5GHz) : +15.5dBm minimum	
	-	5GHz) : +14.5dBm minimum	
		0(5GHz) : +11.5dBm minimum	
	• 802.11ac VHT1	60(5GHz) : +11.5dBm minimum	
Power Consumption	Transmit mode:	2.0 W	
	Receive mode: 1	· · · ·	
		80 mW (WLAN Associated)	
		N (WLAN unassociated) lby/Modern Standby: 10mW	
	Radio disabled: 8	•	
Power Management	ACPI and PCI Exp	ress compliant power management	
.		t power saving mode	
Receiver Sensitivity ³	-	-93.5dBm maximum	
•	802.11b, 11Mbps: -84dBm maximum		
		os: -86dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum		
	802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum		
		-59dBm maximum	
Antenna type		ntenna with spatial diversity, mounted in the display	
	enclosure		
		dual band 2.4/5 GHz antennas are provided to the card to IMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2	MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm		
		57 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g		
	2. Type 126: 1.3]	
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	–40° to 176° F (–40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Rac	lio OFF; LED White – Radio ON	
1. Check latest software/driver release for updates on supported security features.			

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling rate ¹
	BLE: 1 Mbps signaling data rate ¹ 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW
	Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software	Microsoft Windows Bluetooth Software
Supported Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek 802.11a/b/g/n/ac (2x2) Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g



WLAN and Bluetooth® 4.2 Combo ¹	Interoperability Frequency Band	IEEE 802.11n IEEE 802.11ac Wi-Fi® certified 802.11b/g/n •2.402 - 2.482 GHz 802.11a/n •4.9 - 4.95 GHz (Japan) •5.15 - 5.25 GHz •5.25 - 5.35 GHz •5.47 - 5.725 GHz •5.825 - 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi[®] compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum
	Power Consumption	Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 8 mW
	Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
	Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum



	802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Rac	dio OFF; LED White – Radio ON	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.2 Wireless Technology

-	
Bluetooth® Specification	4.0/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹
	BLE: 1 Mbps signaling data rate ¹ Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported	Microsoft Windows Bluetooth Software



Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)



Technical Specifications

POWER

HP 45W Smart	Dimensions (H x W x D)	3.74 x 1.57 x 1.04 in (9.5 >	x 4.0 x 2.65 cm)	
AC Adapter	Weight	0.386 lb (175g) max		
	Input	90 to 265 VAC		
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.4 A at 90 VAC	
	Output	Output power	45W	
		DC output	19.5V	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<8.0A	
	Connector	4.5mm Barrel Type, 3 pin/	grounded, mates with interchangeable cords	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5,000 m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		
HP 65W Smart AC Adapter	Dimensions	90x51x28.5mm		
	Weight	unit: 220g +/- 10g		
	-	Input Efficiency	88% at 115 VAC and 89% at 230 VAC	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.7 A at 90 VAC	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5 ms at 115 VAC input	
		Output current limit	<11A	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cor		
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	



		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	standards - IEC60950, EN approvals - C-UL-US, NOR	with LVD and EMC directives* Worldwide safety 60950, UL60950, Class1, SELV; Agency DICS, DENAN, EN55022 Class B, FCC Class B, M-1 NYCE; MTBF – over 200,000 hours at 25°C
HP 65W EM Smart AC	Dimensions	102x55x30mm	
adapter	Weight	270g +/- 10g	
		Input Efficiency	87% min at 115V/230V
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
		DC output	65W(19.5V/3.33A)
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<11A, Over voltage protection- 29V max automatic shutdown
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	Operating temperature	0° to 35° C
		Non-operating (storage) temperature	-20° to 85° C
		Altitude	0 to 5,000 m
		Humidity	0% to 95%
		Storage Humidity	0% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C ambient condition.	
AC Adapter 65 Watt nPFC	Dimensions	74x74x28.5mm	
USB type C	Weight	unit: 245g +/- 10g	
		Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
		Output power	65W



		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	Туре С	
	Environmental Design	Operating temperature	32°Fto 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	standards - IEC60950, EN6 approvals - C-UL-US, NOR	with LVD and EMC directives* Worldwide safety 50950, UL60950, Class1, SELV; Agency DICS, DENAN, EN55022 Class B, FCC Class B, 1-1 NYCE; MTBF - over 200,000 hours at 25°C
AC Adapter 45 Watt nPFC USB type C	Dimensions	62.0x62.0x28.5mm	
	Weight	unit: 220g +/- 10g	
		Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec:5V : 81.5%9V : 86.7%10V : 87.5%12V : 87.8%15V : 87.8%20V : 87.8%
		Input frequency range	47 ~ 63Hz
		Input AC current	Max. 1.4 A at 90 Vac
		Output power	5V/15W 9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W
		DC output	5V / 9V / 10V /12V / 15V / 20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<5.0A
	Connector	Туре С	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%



	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C ambient condition.
3 Cell WHr 45 Long Life - Polymer HP Fast Charge Technology ¹	Dimensions	6.0. x184.7x88.9 mm
	Weight	0.22 kg (0.48lb)
	Cells/Type	3cell Lithium-Ion
	Voltage	11.55V
	Amp-hour capacity	3.900Ah
	Watt-hour capacity	45Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)
1. Recharges the battery (up to 50% within 30 minutes	when the system is off or in standby mode when used with the power

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

Country of Origin China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP Essential Messenger Case	H1D25AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
Memory	4GB 2666MHz DDR4	4VN05AA
	8GB 2666MHz DDR4	4VN06AA
	16GB 2666 MHz DDR4	4VN07AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Power Adapter	3PN48AA
	HP 45W USB-C Power Adapter	1HE17AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP Power Bank	N9F71AA
	HP USB-C Power Bank	2NA10AA
	HP 45W LC USB-C Power Adapter	1MZ01AA#ABA
Storage	HP External USB Optical Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
Security	HP Combination Lock	TOY15AA
	HP Essential Keyed Cable lock 12.3mm	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP UltraSlim Keyed Cable Lock	T1A62AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP Speaker Phone	K7V16AA
	HP Wired Headset	K7V17AA
Displays	HP ProDisplay P223 21.5-inch Monitor	X7R61AA
	HP ProDisplay P232 23-inch Monitor	K7X31AA
	HP ProDisplay P240va 23.8-inch Monitor	X3B48AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E243m 23.8-inch Collaboration Monitor	1FH48AA
	HP EliteDisplay E273 27-inch Monitor	1FH50AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 10, 2018	V1 to V2	Removed	Dock UltraSlim
December 12, 2018	V2 to V3	Removed	Phonewise Software
December 17, 2018	V3 to V4	Added	Environmental section
December 21, 2018	V4 to V5	Added	Skype in at a glance section
January 30, 2019	V5 to V6	Added	Storage section
March 7, 2019	V6 to V7	Updated	Passed MIL-STD
March 15, 2019	V7 to V8	Added	Processors
March 20, 2019	V8 to V9	Updated	Storage and drives
April 17, 2019	V9 to V10	Updated	MIL-STD
May 7, 2019	V10 to V11	Updated	At a glance section
June 11, 2019	V11 to V12	Added	HP Cloud Recovery
July 23, 2019	V12 to V13	Added	Speaker to Audio section

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